

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: T.L. Ritzdorf et al. Attorney Docket No.: SEMT117192  
Application No.: Filed Concurrently Herewith Group Art Unit: --  
Filed: Concurrently Herewith Examiner: --  
Title: METHOD FOR FILLING RECESSED MICROSTRUCTURES WITH  
METALLIZATION IN THE PRODUCTION OF A MICROELECTRONIC  
DEVICE

6/A

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PRELIMINARY AMENDMENT

Seattle, Washington 98101

June 12, 2001

3/11/03

TO THE COMMISSIONER FOR PATENTS:

Prior to examination, please amend the above-identified application as follows:

In the Specification:

Please amend the specification as follows:

On page 1, line 6, beneath the heading "CROSS-REFERENCE TO RELATED APPLICATIONS", please delete the words "Not Applicable" and insert the following new paragraph:

This application is a continuation of prior U.S. Patent Application No. 09/018,783, filed February 4, 1998, the disclosure of which is hereby incorporated by reference, and priority from which is hereby claimed under 35 U.S.C. § 120.

In the Claims:

Please cancel Claims 1-31.

Please add new Claims 32-53 as follows:

32. (New) A process for electrochemical deposition of metal onto a surface of a microelectronic workpiece, comprising:

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